

Title (en)

COMPOSITION FOR MATTING AND REDUCING ANTI-FINGERPRINT EFFECTS ON SURFACES OF SUBSTRATE MATERIALS

Title (de)

ZUSAMMENSETZUNG ZUR MATTIERUNG UND REDUZIERUNG VON ANTI-FINGERPRINT-EFFEKTEN VON OBERFLÄCHEN AUF TRÄGERMATERIALIEN

Title (fr)

COMPOSITION POUR LE MATAGE ET LA RÉDUCTION DES EFFETS ANTI-EMPREINTES DE SURFACES SUR DES MATÉRIAUX SUPPORT

Publication

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Application

EP 21725967 A 20210427

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Abstract (en)

[origin: WO2021219640A1] The invention relates to a resin suspension based on a formaldehyde resin comprising a composition for matting and reducing anti-fingerprint effects on surfaces of substrate materials, in particular paper layers and wood boards, wherein the composition has silane compounds and at least one matting agent. The invention additionally relates to a method for producing same, to the use of said composition, and to substrate materials, such as paper layers or wood boards, comprising said composition.

IPC 8 full level

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